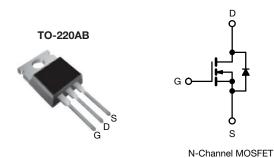
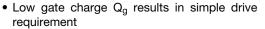


Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	400			
R _{DS(on)} (Ω)	$V_{GS} = 10 \text{ V}$	1.0		
Q _g max. (nC)	22			
Q _{gs} (nC)	5.8			
Q _{gd} (nC)	9.3			
Configuration	Single			

FEATURES





Improved gate, avalanche and dynamic dV/dt ruggedness

- RoHS*
- Fully characterized capacitance and avalanche voltage and current
- Effective Coss specified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- · High speed power switching

TYPICAL SMPS TOPOLOGIES

- Single transistor flyback Xfmr. reset
- Single transistor forward Xfmr. reset (both US line input only)

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF730APbF		
Lead (Pb)-free and halogen-free	IRF730APbF-BE3		

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	400	V	
Gate-source voltage			V_{GS}	± 30	7 v	
Continuous drain current	V -+ 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	5.5		
	V _{GS} at 10 V	T _C = 100 °C		3.5	Α	
Pulsed drain current ^a			I _{DM}	22		
Linear derating factor				0.6	W/°C	
Single pulse avalanche energy b			E _{AS}	290	mJ	
Repetitive avalanche current a			I _{AR}	5.5	А	
Repetitive avalanche energy ^a			E _{AR}	7.4	mJ	
Maximum power dissipation	T _C =	25 °C	P_{D}	74	W	
Peak diode recovery dV/dt ^c			dV/dt	4.6	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^d	For 10 s			300	7	
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Starting $T_J = 25$ °C, L = 19 mH, $R_g = 25 \Omega$, $I_{AS} = 5.5$ A (see fig. 12)
- c. $I_{SD} \le 5.5$ Å, $dI/dt \le 90$ Å/µs, $V_{DD} \le V_{DS}$, $T_{J} \le 150$ °C
- d. 1.6 mm from case



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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R _{thJC}	-	1.70			
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W		
Maximum junction-to-case (drain)	R _{thJA}	-	62			

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static					L	L	l
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		400	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.5	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.5	V
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$		-	± 100	nA
Zava sata valtasa duain augusat		V _{DS} = 400 V, V _{GS} = 0 V		-	-	25	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 320 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	250	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.3 A ^b	-	-	1.0	Ω
Forward transconductance	9 _{fs}	V _{DS} = 50 V, I _D = 3.3 A		3.1	-	=.	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ f = 1.0 MHz, see fig. 5		-	600	-	-
Output capacitance	C _{oss}			-	103	-	
Reverse transfer capacitance	C _{rss}			-	4.0	-	
Output capacitance		V _{GS} = 0 V	$V_{DS} = 1.0 \text{ V}, f = 1.0 \text{ MHz}$	-	890	-	pF -
	C_{oss}		V _{DS} = 320 V, f = 1.0 MHz	=	30	-	
Effective output capacitance	Coss eff.		$V_{DS} = 0 \text{ V to } 320 \text{ V}^{\text{ c}}$	-	45	=.	
Total gate charge	Qg		V _{GS} = 10 V I _D = 3.5 A, V _{DS} = 320 V see fig. 6 and 13 b	-	-	22	nC
Gate-source charge	Q _{gs}	V _{GS} = 10 V		=	-	5.8	
Gate-drain charge	Q_{gd}		geo ng. o ana ro	-	-	9.3	
Turn-on delay time	t _{d(on)}			-	10	-	
Rise time	t _r	$\begin{array}{c} \text{V}_{DD} = 200 \text{ V, I}_D = 3.5 \text{ A} \\ \text{R}_g = 12 \ \Omega, \ \text{R}_D = 57 \ \Omega, \\ \text{see fig. 10} \ ^b \end{array}$		-	22	-	ns
Turn-off delay time	t _{d(off)}			-	20	-	
Fall time	t _f			-	16	-	
Gate input resistance	R _g	f = 1 MHz, open drain		2.7	-	10.9	Ω
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		ı	ı	5.5	_
Pulsed diode forward current ^a	I _{SM}			-	-	22	A
Body diode voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 5.5 \text{A}, V_{GS} = 0 ^{\circ}\text{V}^{\text{b}}$		-	-	1.6	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 3.5 A, dl/dt = 100 A/µs b		-	370	550	ns
Body diode reverse recovery charge	Q _{rr}			-	1.6	2.4	μC
Forward turn-on time	t _{on}	Intrinsic tu	ırn-on time is negligible (turn	on is dor	ninated b	v Ls and	Ln)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %
- c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

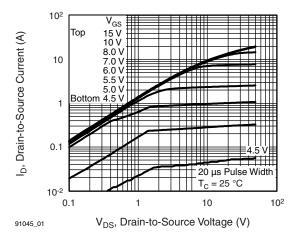


Fig. 1 - Typical Output Characteristics

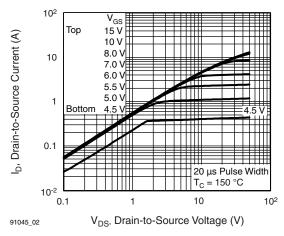


Fig. 2 - Typical Output Characteristics

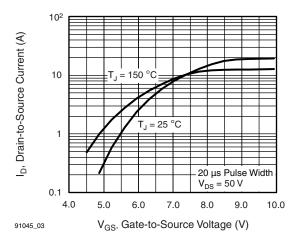


Fig. 3 - Typical Transfer Characteristics

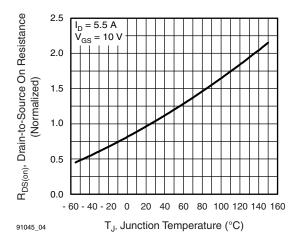


Fig. 4 - Normalized On-Resistance vs. Temperature

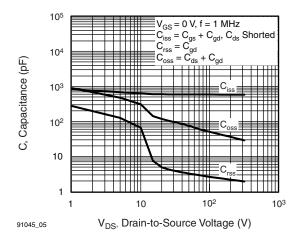


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

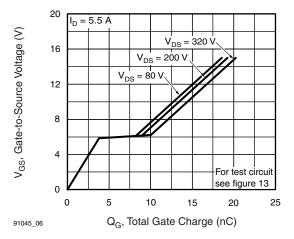


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



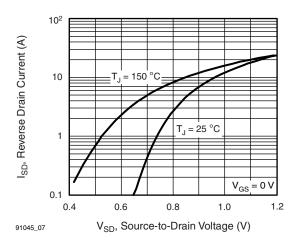


Fig. 7 - Typical Source-Drain Diode Forward Voltage

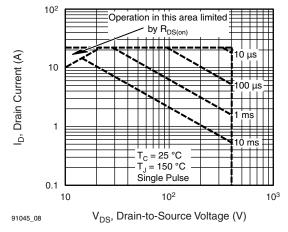


Fig. 8 - Maximum Safe Operating Area

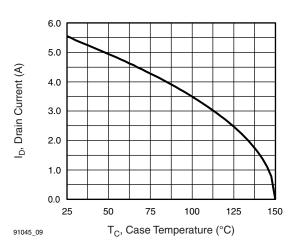


Fig. 9 - Maximum Drain Current vs. Case Temperature

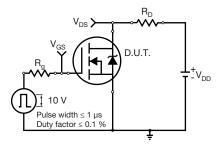


Fig. 10 - Switching Time Test Circuit

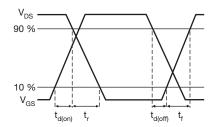


Fig. 11 - Switching Time Waveforms

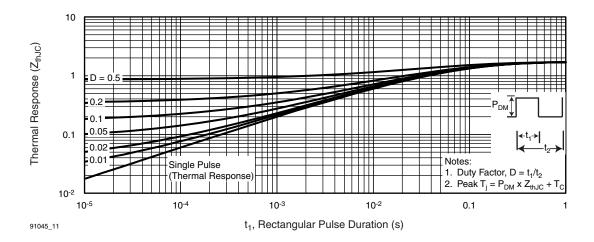




Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

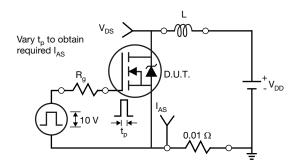


Fig. 13 - Unclamped Inductive Test Circuit

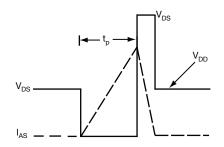


Fig. 14 - Unclamped Inductive Waveforms

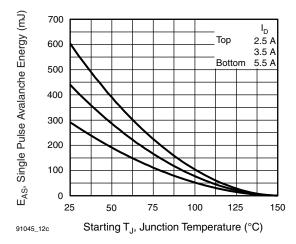


Fig. 15 - Maximum Avalanche Energy vs. Drain Current

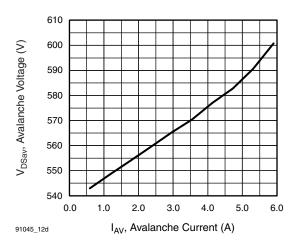


Fig. 16 - Typical Drain Source Voltage vs. Avalanche Current

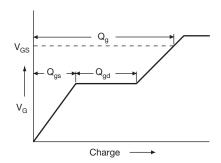


Fig. 17 - Basic Gate Charge Waveform

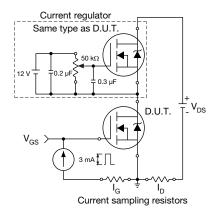
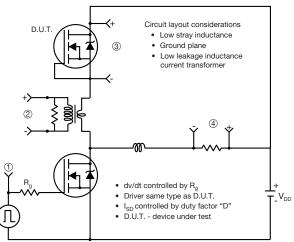


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



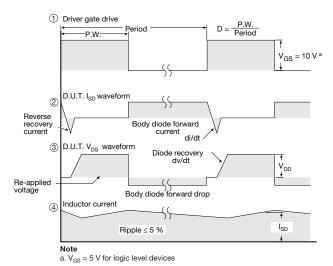


Fig. 19 - For N-Channel

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